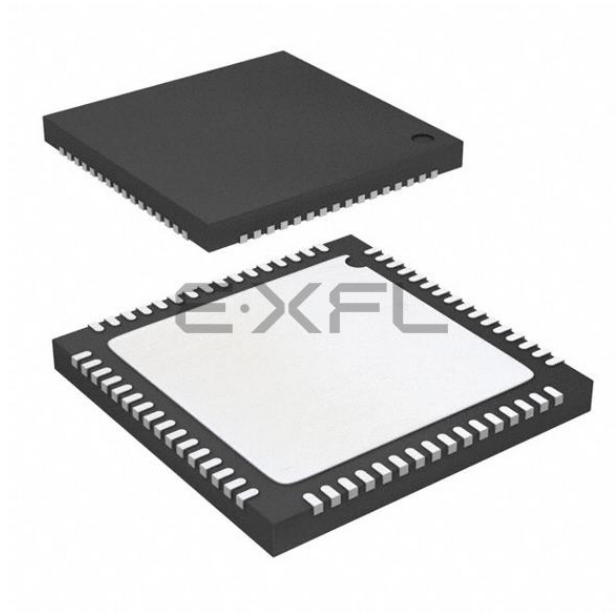

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM7®
Core Size	16/32-Bit
Speed	44MHz
Connectivity	EBI/EMI, I²C, SPI, UART/USART
Peripherals	PLA, PWM, PSM, Temp Sensor, WDT
Number of I/O	30
Program Memory Size	62KB (31K x16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 32
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	A/D 10x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad, CSP
Supplier Device Package	64-LFCSP-VQ (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/analog-devices/aduc7024bcpz62i

GENERAL DESCRIPTION

The ADuC7019/20/21/22/24/25/26/27/28/29 are fully integrated, 1 MSPS, 12-bit data acquisition systems incorporating high performance multichannel ADCs, 16-bit/32-bit MCUs, and Flash®/EE memory on a single chip.

The ADC consists of up to 12 single-ended inputs. An additional four inputs are available but are multiplexed with the four DAC output pins. The four DAC outputs are available only on certain models (ADuC7020, ADuC7026, ADuC7028, and ADuC7029). However, in many cases where the DAC outputs are not present, these pins can still be used as additional ADC inputs, giving a maximum of 16 ADC input channels. The ADC can operate in single-ended or differential input mode. The ADC input voltage is 0 V to V_{REF}. A low drift band gap reference, temperature sensor, and voltage comparator complete the ADC peripheral set.

Depending on the part model, up to four buffered voltage output DACs are available on-chip. The DAC output range is programmable to one of three voltage ranges.

The devices operate from an on-chip oscillator and a PLL generating an internal high frequency clock of 41.78 MHz (UCLK). This clock is routed through a programmable clock divider from which the MCU core clock operating frequency is generated. The microcontroller core is an ARM7TDMI®, 16-bit/32-bit RISC machine, which offers up to 41 MIPS peak performance. Eight kilobytes of SRAM and 62 kilobytes of nonvolatile Flash/EE memory are provided on-chip. The ARM7TDMI core views all memory and registers as a single linear array.

On-chip factory firmware supports in-circuit serial download via the UART or I²C serial interface port; nonintrusive emulation is also supported via the JTAG interface. These features are incorporated into a low cost QuickStart™ development system supporting this MicroConverter® family.

The parts operate from 2.7 V to 3.6 V and are specified over an industrial temperature range of −40°C to +125°C. When operating at 41.78 MHz, the power dissipation is typically 120 mW. The ADuC7019/20/21/22/24/25/26/27/28/29 are available in a variety of memory models and packages (see Ordering Guide).

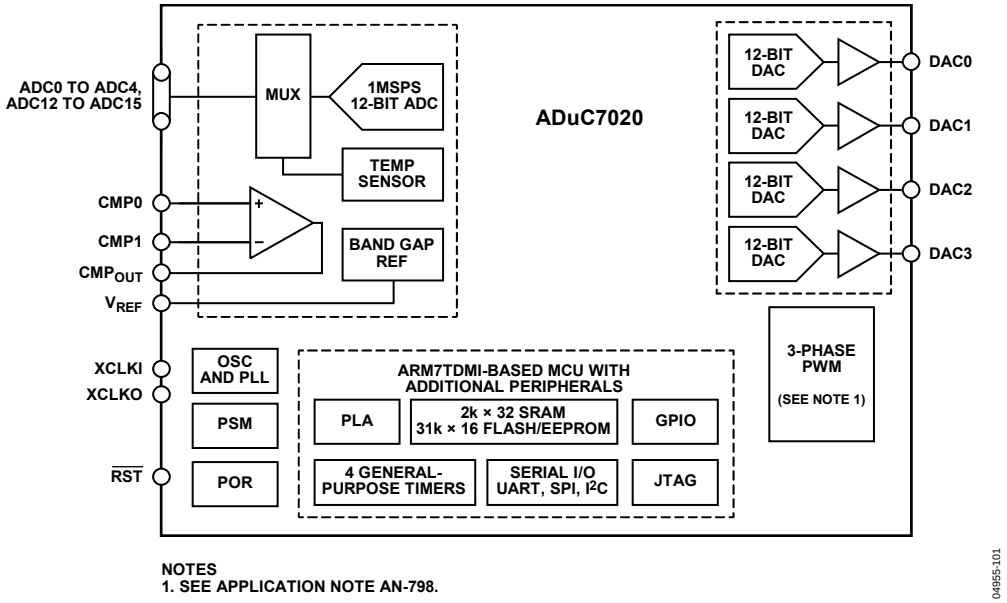


Figure 2.

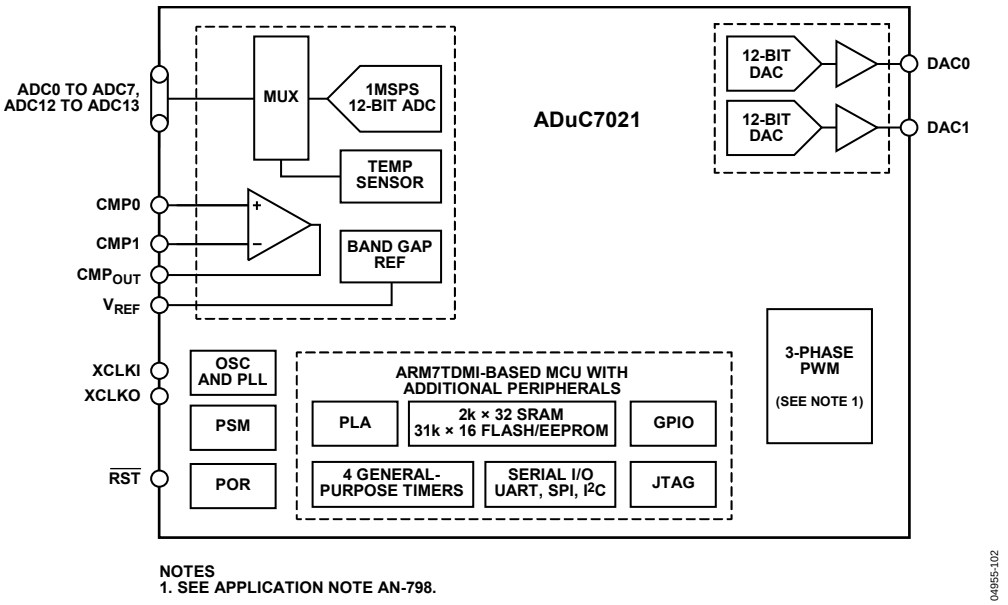


Figure 3.

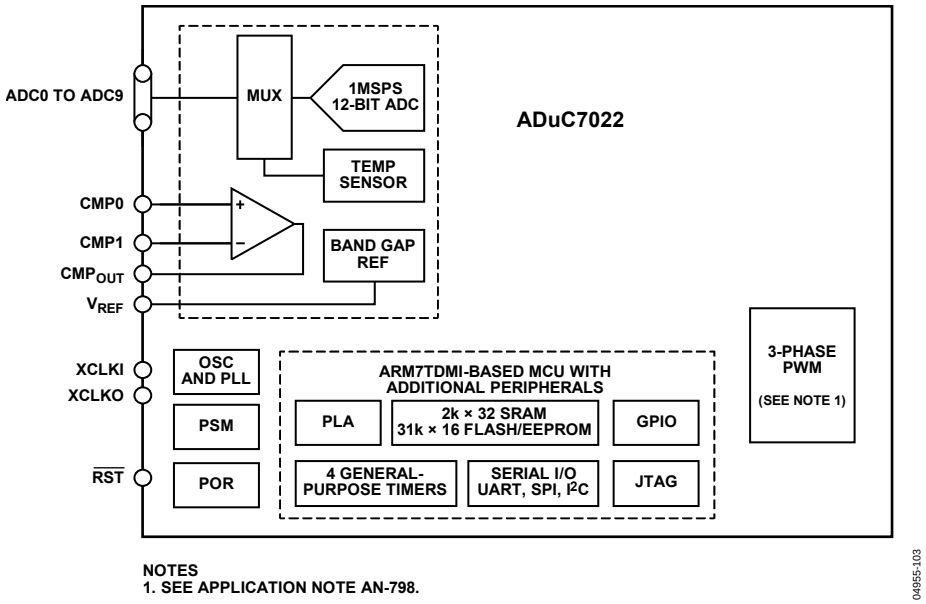
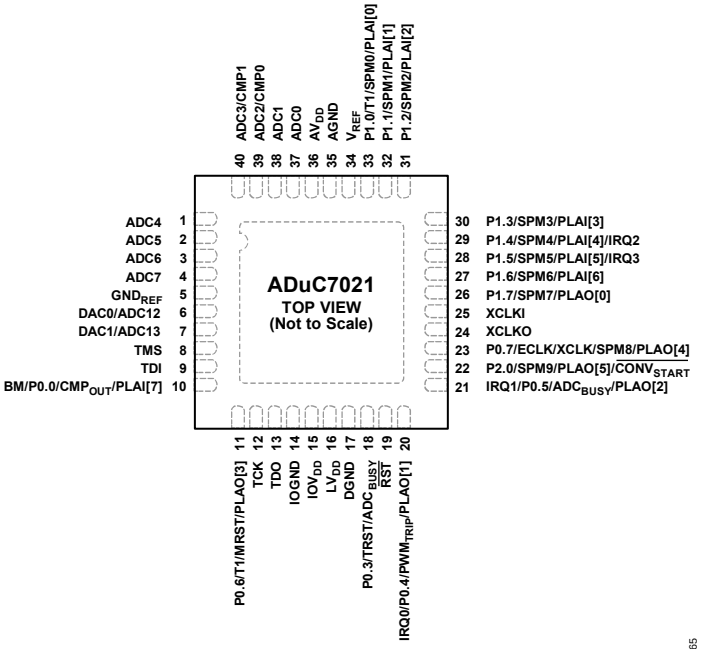


Figure 4.

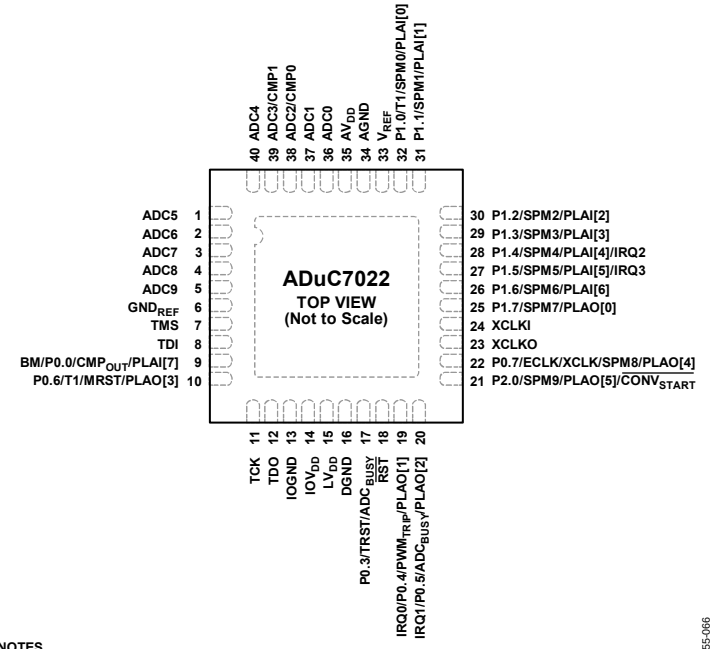
Parameter	Min	Typ	Max	Unit	Test Conditions/Comments
DAC AC CHARACTERISTICS					
Voltage Output Settling Time		10		µs	
Digital-to-Analog Glitch Energy		±20		nV-sec	1 LSB change at major carry (where maximum number of bits simultaneously changes in the DACxDAT register)
COMPARATOR					
Input Offset Voltage		±15		mV	
Input Bias Current		1		µA	
Input Voltage Range	AGND		AV_{DD} – 1.2	V	
Input Capacitance		7		pF	
Hysteresis[4, 6]	2		15	mV	Hysteresis turned on or off via the CMPHYST bit in the CMPCON register
Response Time		3		µs	100 mV overdrive and configured with CMPRES = 11
TEMPERATURE SENSOR					
Voltage Output at 25°C		780		mV	
Voltage TC		−1.3		mV/°C	
Accuracy		±3		°C	
POWER SUPPLY MONITOR (PSM)					
IOV_{DD} Trip Point Selection		2.79		V	Two selectable trip points
		3.07		V	
Power Supply Trip Point Accuracy		±2.5		%	Of the selected nominal trip point voltage
POWER-ON-RESET		2.36		V	
GLITCH IMMUNITY ON RESET PIN[4]		50		µs	
WATCHDOG TIMER (WDT)					
Timeout Period	0		512	sec	
FLASH/EE MEMORY					
Endurance[9]	10,000			Cycles	
Data Retention[10]	20			Years	T_J = 85°C
DIGITAL INPUTS					All digital inputs excluding XCLKI and XCLKO
Logic 1 Input Current		±0.2	±1	µA	V_{IH} = IOV_{DD} or V_{IH} = 5 V
Logic 0 Input Current		−40	−60	µA	V_{IL} = 0 V; except TDI on ADuC7019/20/21/22/24/25/29
		−80	−120	µA	V_{IL} = 0 V; TDI on ADuC7019/20/21/22/24/25/29
Input Capacitance		10		pF	
LOGIC INPUTS[3]					All logic inputs excluding XCLKI
V_{INL}, Input Low Voltage			0.8	V	
V_{INH}, Input High Voltage	2.0			V	
LOGIC OUTPUTS					All digital outputs excluding XCLKO
V_{OH}, Output High Voltage	2.4			V	I_{SOURCE} = 1.6 mA
V_{OL}, Output Low Voltage[11]			0.4	V	I_{SINK} = 1.6 mA
CRYSTAL INPUTS XCLKI and XCLKO					
Logic Inputs, XCLKI Only					
V_{INL}, Input Low Voltage		1.1		V	
V_{INH}, Input High Voltage		1.7		V	
XCLKI Input Capacitance		20		pF	
XCLKO Output Capacitance		20		pF	
INTERNAL OSCILLATOR		32.768		kHz	
			±3	%	
			±2[4]	%	T_A = 0°C to 85°C range



NOTES
1. THE EXPOSED PAD MUST BE SOLDERED FOR MECHANICAL PURPOSES AND LEFT UNCONNECTED.

04955-065

Figure 21. 40-Lead LFCSP_WQ Pin Configuration (ADuC7021)



NOTES
1. THE EXPOSED PAD MUST BE SOLDERED FOR MECHANICAL PURPOSES AND LEFT UNCONNECTED.

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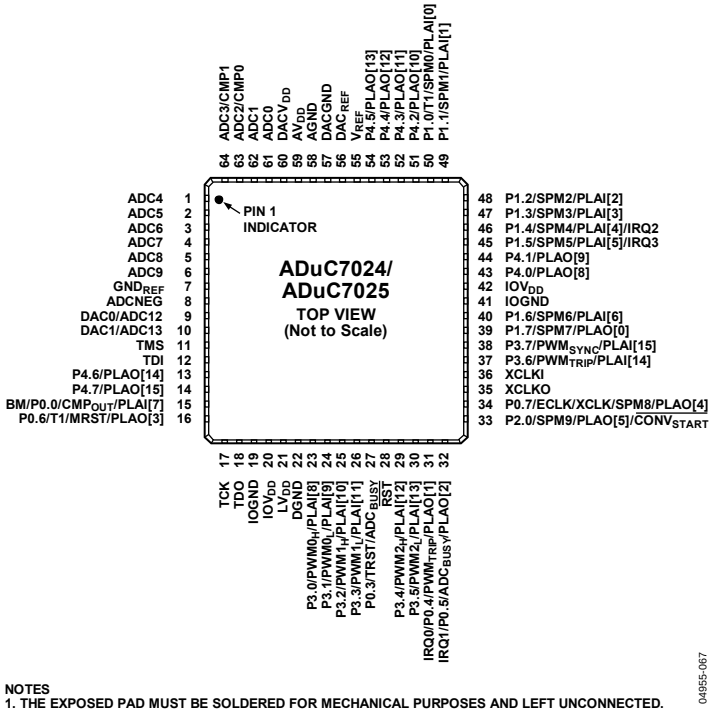
Figure 22. 40-Lead LFCSP_WQ Pin Configuration (ADuC7022)

ADuC7024/ADuC7025



NOTES
1. THE EXPOSED PAD MUST BE SOLDERED FOR MECHANICAL PURPOSES AND LEFT UNCONNECTED.

Figure 23. 64-Lead LFCSP_VQ Pin Configuration (ADuC7024/ADuC7025)

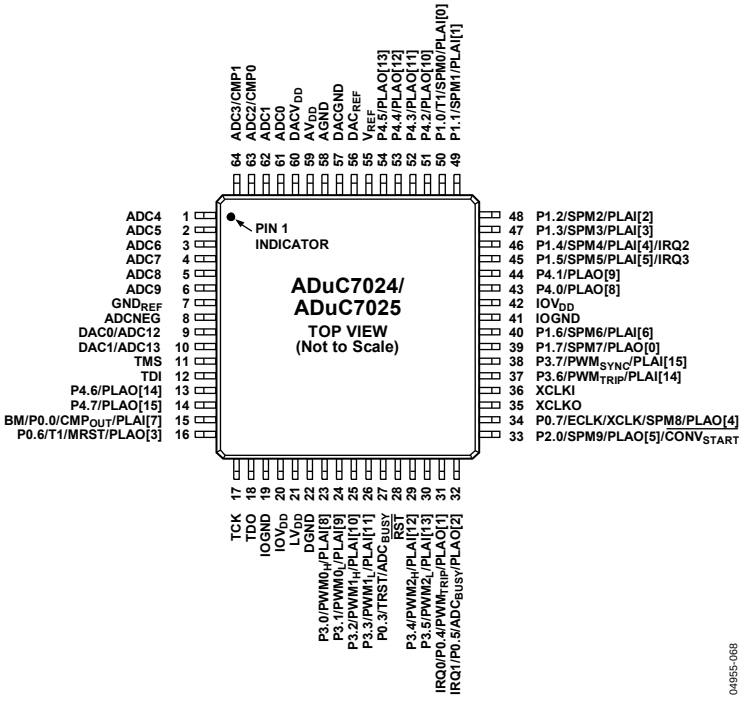


Figure 24. 64-Lead LQFP Pin Configuration (ADuC7024/ADuC7025)

Pin No.	Mnemonic	Description
E1	TMS	JTAG Test Port Input, Test Mode Select. Debug and download access.
E2	BM/P0.0/CMP_{OUT}/PLAI[7]	Multifunction I/O Pin. Boot mode. The ADuC7029 enters UART download mode if BM is low at reset and executes code if BM is pulled high at reset through a 1 kΩ resistor/General-Purpose Input and Output Port 0.0/Voltage Comparator Output/Programmable Logic Array Input Element 7.
E3	DAC2/ADC14	DAC2 Voltage Output/ADC Input 14.
E4	IOV_{DD}	3.3 V Supply for GPIO (see Table 78) and Input of the On-Chip Voltage Regulator.
E5	P3.2/$PWM1_H$/PLAI[10]	General-Purpose Input and Output Port 3.2/PWM Phase 1 High-Side Output/Programmable Logic Array Input Element 10.
E6	P3.5/$PWM2_L$/PLAI[13]	General-Purpose Input and Output Port 3.5/PWM Phase 2 Low-Side Output/Programmable Logic Array Input Element 13.
E7	P0.7/ECLK/XCLK/SPM8/PLAO[4]	Serial Port Multiplexed. General-Purpose Input and Output Port 0.7/Output for External Clock Signal/Input to the Internal Clock Generator Circuits/UART/Programmable Logic Array Output Element 4.
F1	TDI	JTAG Test Port Input, Test Data In. Debug and download access.
F2	P0.6/T1/MRST/PLAO[3]	Multifunction Pin, Driven Low After Reset. General-Purpose Output Port 0.6/Timer1 Input/Power-On Reset Output/Programmable Logic Array Output Element 3.
F3	IOGND	Ground for GPIO (see Table 78). Typically connected to DGND.
F4	P3.1/$PWM0_L$/PLAI[9]	General-Purpose Input and Output Port 3.1/PWM Phase 0 Low-Side Output/Programmable Logic Array Input Element 9.
F5	P3.0/$PWM0_H$/PLAI[8]	General-Purpose Input and Output Port 3.0/PWM Phase 0 High-Side Output/Programmable Logic Array Input Element 8.
F6	$\overline{RST}$	Reset Input, Active Low.
F7	P2.0/SPM9/PLAO[5]/$\overline{CONV_{START}}$	Serial Port Multiplexed. General-Purpose Input and Output Port 2.0/UART/Programmable Logic Array Output Element 5/Start Conversion Input Signal for ADC.
G1	TCK	JTAG Test Port Input, Test Clock. Debug and download access.
G2	TDO	JTAG Test Port Output, Test Data Out. Debug and download access.
G3	LV_{DD}	2.6 V Output of the On-Chip Voltage Regulator. This output must be connected to a 0.47 µF capacitor to DGND only.
G4	DGND	Ground for Core Logic.
G5	P0.3/TRST/ADC_{BUSY}	General-Purpose Input and Output Port 0.3/JTAG Test Port Input, Test Reset/ADC_{BUSY} Signal Output.
G6	IRQ0/P0.4/PWM_{TRIP}/PLAO[1]	Multifunction I/O Pin. External Interrupt Request 0, Active High/General-Purpose Input and Output Port 0.4/PWM Trip External Input/Programmable Logic Array Output Element 1.
G7	IRQ1/P0.5/ADC_{BUSY}/PLAO[2]	Multifunction I/O Pin. External Interrupt Request 1, Active High/General-Purpose Input and Output Port 0.5/ADC_{BUSY} Signal Output/Programmable Logic Array Output Element 2.

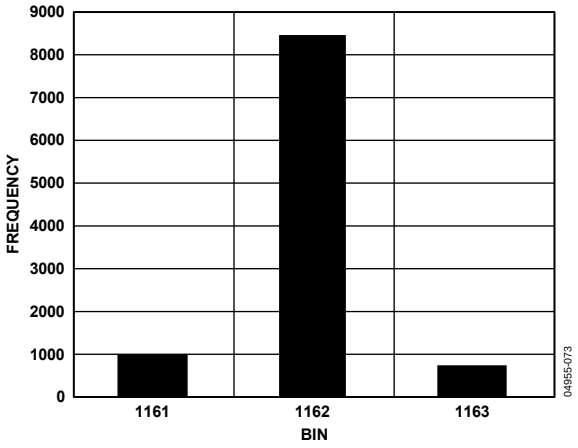


Figure 34. Code Histogram Plot, fs = 774 kSPS, V_{IN} = 0.7 V

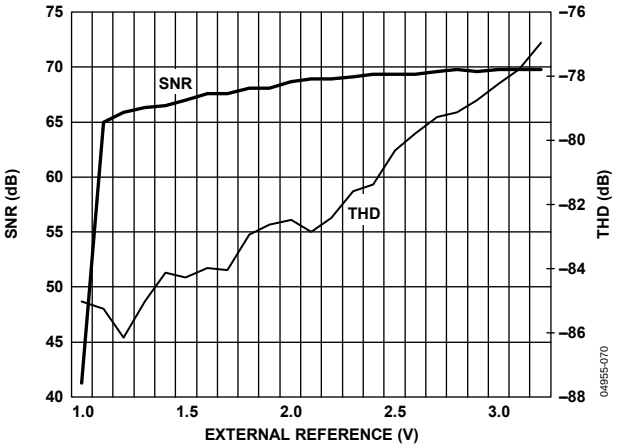


Figure 37. Typical Dynamic Performance vs. V_{REF}

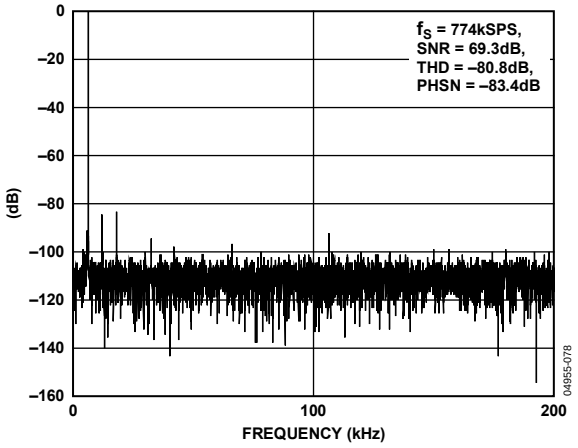


Figure 35. Dynamic Performance, f_S = 774 kSPS

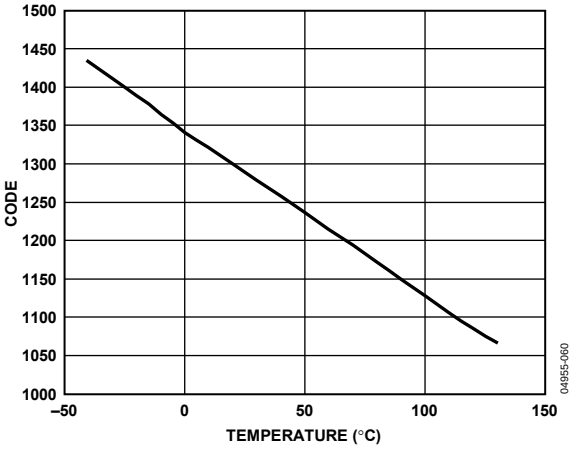


Figure 38. On-Chip Temperature Sensor Voltage Output vs. Temperature

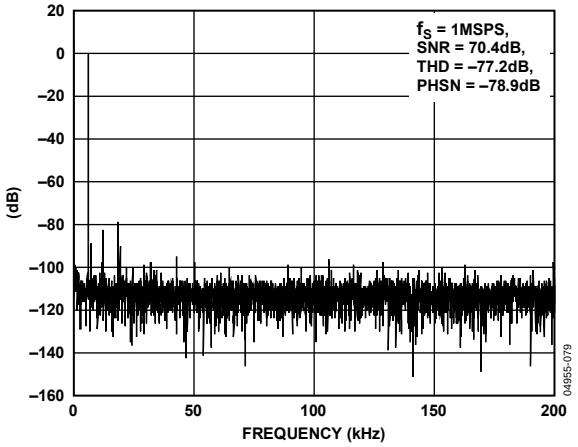


Figure 36. Dynamic Performance, f_S = 1 MSPS

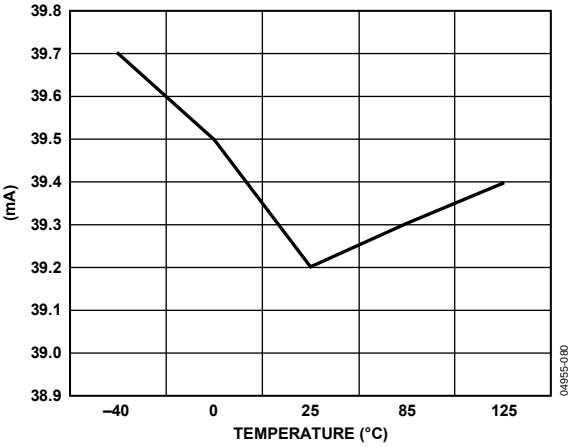


Figure 39. Current Consumption vs. Temperature @ CD = 0

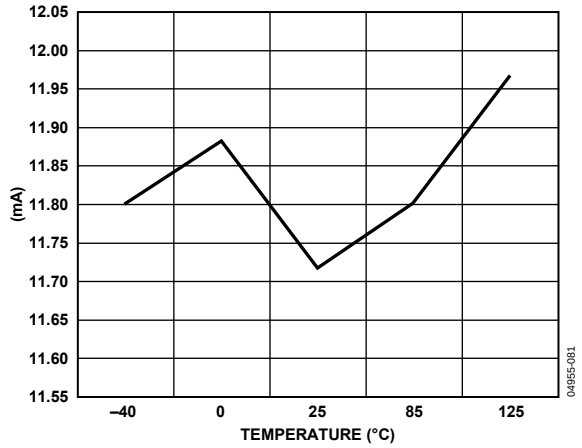


Figure 40. Current Consumption vs. Temperature @ CD = 3

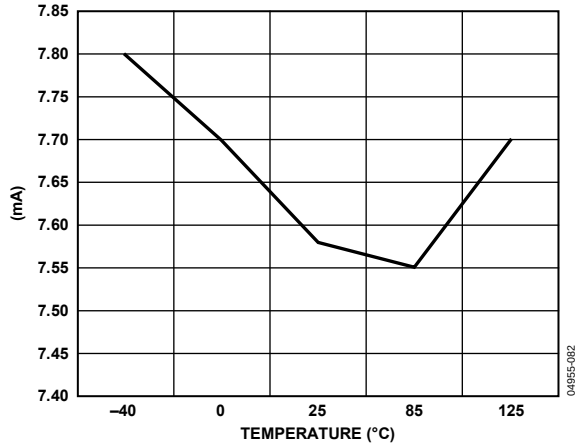


Figure 41. Current Consumption vs. Temperature @ CD = 7

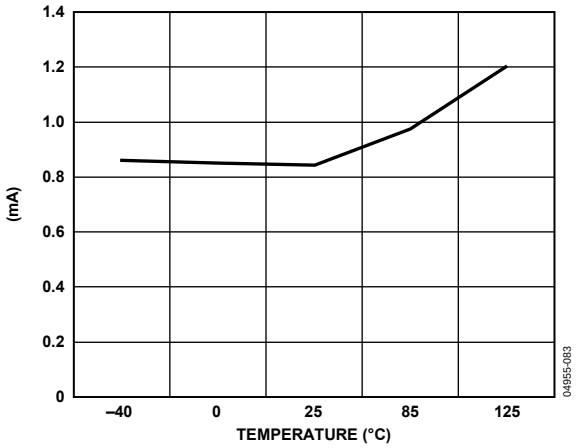


Figure 42. Current Consumption vs. Temperature in Sleep Mode

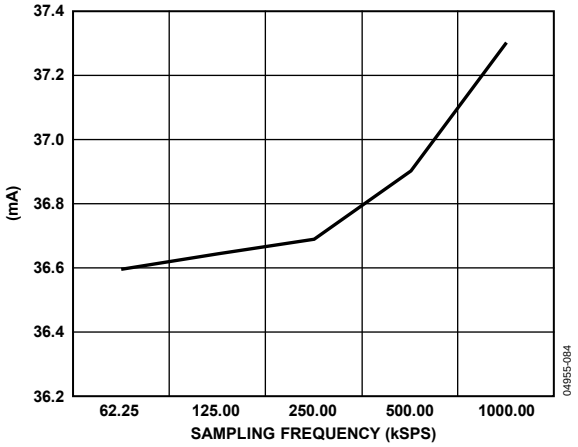


Figure 43. Current Consumption vs. Sampling Frequency

MEMORY ORGANIZATION

The ADuC7019/20/21/22/24/25/26/27/28/29 incorporate two separate blocks of memory: 8 kB of SRAM and 64 kB of on-chip Flash/EE memory. The 62 kB of on-chip Flash/EE memory is available to the user, and the remaining 2 kB are reserved for the factory-configured boot page. These two blocks are mapped as shown in Figure 45.

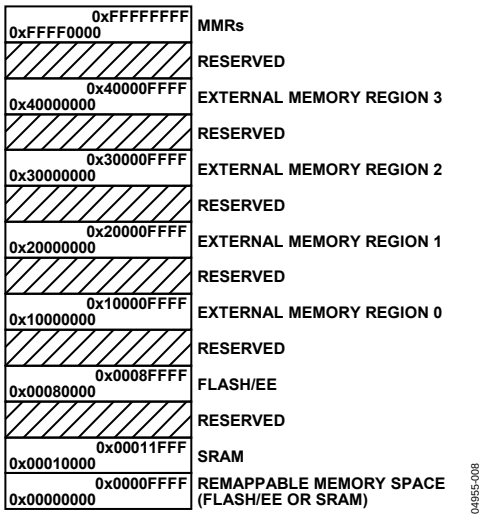


Figure 45. Physical Memory Map

Note that by default, after a reset, the Flash/EE memory is mirrored at Address 0x00000000. It is possible to remap the SRAM at Address 0x00000000 by clearing Bit 0 of the REMAP MMR. This remap function is described in more detail in the Flash/EE Memory section.

MEMORY ACCESS

The ARM7 core sees memory as a linear array of a 2^{32} byte location where the different blocks of memory are mapped as outlined in Figure 45.

The ADuC7019/20/21/22/24/25/26/27/28/29 memory organizations are configured in little endian format, which means that the least significant byte is located in the lowest byte address, and the most significant byte is in the highest byte address.

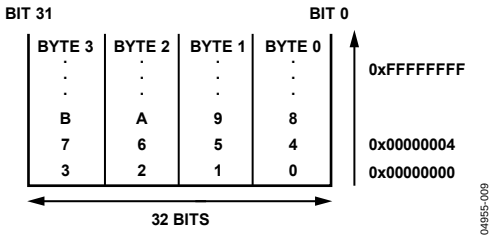


Figure 46. Little Endian Format

FLASH/EE MEMORY

The total 64 kB of Flash/EE memory is organized as 32 k × 16 bits; 31 k × 16 bits is user space and 1 k × 16 bits is reserved for the on-chip kernel. The page size of this Flash/EE memory is 512 bytes.

Sixty-two kilobytes of Flash/EE memory are available to the user as code and nonvolatile data memory. There is no distinction between data and program because ARM code shares the same space. The real width of the Flash/EE memory is 16 bits, which means that in ARM mode (32-bit instruction), two accesses to the Flash/EE are necessary for each instruction fetch. It is therefore recommended to use thumb mode when executing from Flash/EE memory for optimum access speed. The maximum access speed for the Flash/EE memory is 41.78 MHz in thumb mode and 20.89 MHz in full ARM mode. More details about Flash/EE access time are outlined in the Execution Time from SRAM and Flash/EE section.

SRAM

Eight kilobytes of SRAM are available to the user, organized as 2 k × 32 bits, that is, two words. ARM code can run directly from SRAM at 41.78 MHz, given that the SRAM array is configured as a 32-bit wide memory array. More details about SRAM access time are outlined in the Execution Time from SRAM and Flash/EE section.

MEMORY MAPPED REGISTERS

The memory mapped register (MMR) space is mapped into the upper two pages of the memory array and accessed by indirect addressing through the ARM7 banked registers.

The MMR space provides an interface between the CPU and all on-chip peripherals. All registers, except the core registers, reside in the MMR area. All shaded locations shown in Figure 47 are unoccupied or reserved locations and should not be accessed by user software. Table 16 shows the full MMR memory map.

The access time for reading from or writing to an MMR depends on the advanced microcontroller bus architecture (AMBA) bus used to access the peripheral. The processor has two AMBA buses: the advanced high performance bus (AHB) used for system modules and the advanced peripheral bus (APB) used for lower performance peripheral. Access to the AHB is one cycle, and access to the APB is two cycles. All peripherals on the ADuC7019/20/21/22/24/25/26/27/28/29 are on the APB except the Flash/EE memory, the GPIOs (see Table 78), and the PWM.

ADC CIRCUIT OVERVIEW

The analog-to-digital converter (ADC) incorporates a fast, multichannel, 12-bit ADC. It can operate from 2.7 V to 3.6 V supplies and is capable of providing a throughput of up to 1 MSPS when the clock source is 41.78 MHz. This block provides the user with a multichannel multiplexer, a differential track-and-hold, an on-chip reference, and an ADC.

The ADC consists of a 12-bit successive approximation converter based around two capacitor DACs. Depending on the input signal configuration, the ADC can operate in one of three modes.

- Fully differential mode, for small and balanced signals
- Single-ended mode, for any single-ended signals
- Pseudo differential mode, for any single-ended signals, taking advantage of the common-mode rejection offered by the pseudo differential input

The converter accepts an analog input range of 0 V to V_{REF} when operating in single-ended or pseudo differential mode. In fully differential mode, the input signal must be balanced around a common-mode voltage (V_{CM}) in the 0 V to AV_{DD} range with a maximum amplitude of 2 V_{REF} (see Figure 48).

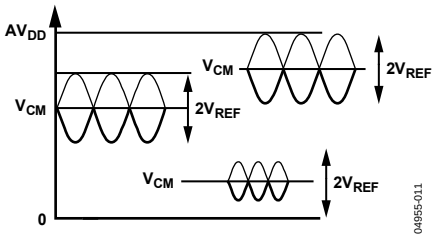


Figure 48. Examples of Balanced Signals in Fully Differential Mode

A high precision, low drift, factory calibrated, 2.5 V reference is provided on-chip. An external reference can also be connected as described in the Band Gap Reference section.

Single or continuous conversion modes can be initiated in the software. An external $\overline{CONV_{START}}$ pin, an output generated from the on-chip PLA, or a Timer0 or Timer1 overflow can also be used to generate a repetitive trigger for ADC conversions.

A voltage output from an on-chip band gap reference proportional to absolute temperature can also be routed through the front-end ADC multiplexer, effectively an additional ADC channel input. This facilitates an internal temperature sensor channel that measures die temperature to an accuracy of ±3°C.

TRANSFER FUNCTION

Pseudo Differential and Single-Ended Modes

In pseudo differential or single-ended mode, the input range is 0 V to V_{REF}. The output coding is straight binary in pseudo differential and single-ended modes with

1 LSB = *FS*/4096, or
2.5 V/4096 = 0.61 mV, or
610 µV when V_{REF} = 2.5 V

The ideal code transitions occur midway between successive integer LSB values (that is, 1/2 LSB, 3/2 LSB, 5/2 LSB, … , FS – 3/2 LSB). The ideal input/output transfer characteristic is shown in Figure 49.

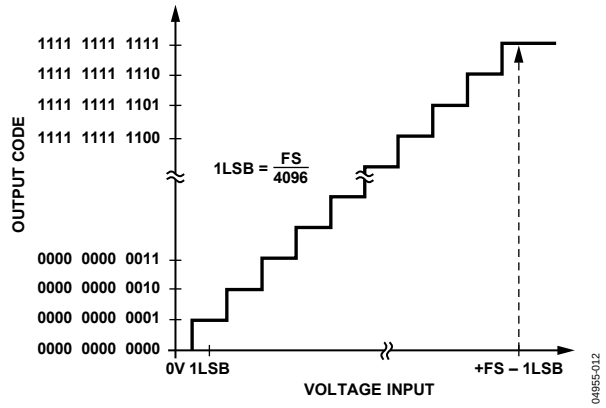


Figure 49. ADC Transfer Function in Pseudo Differential or Single-Ended Mode

Fully Differential Mode

The amplitude of the differential signal is the difference between the signals applied to the V_{IN+} and V_{IN-} input voltage pins (that is, $V_{IN+} - V_{IN-}$). The maximum amplitude of the differential signal is, therefore, $-V_{REF}$ to $+V_{REF}$ p-p (that is, $2 \times V_{REF}$). This is regardless of the common mode (CM). The common mode is the average of the two signals, for example, $(V_{IN+} + V_{IN-})/2$, and is, therefore, the voltage that the two inputs are centered on. This results in the span of each input being CM ± $V_{REF}/2$. This voltage has to be set up externally, and its range varies with V_{REF} (see the Driving the Analog Inputs section).

The output coding is twos complement in fully differential mode with 1 LSB = 2 $V_{REF}/4096$ or 2 × 2.5 V/4096 = 1.22 mV when V_{REF} = 2.5 V. The output result is ±11 bits, but this is shifted by 1 to the right. This allows the result in ADCDAT to be declared as a signed integer when writing C code. The designed code transitions occur midway between successive integer LSB values (that is, 1/2 LSB, 3/2 LSB, 5/2 LSB, … , FS – 3/2 LSB). The ideal input/output transfer characteristic is shown in Figure 50.

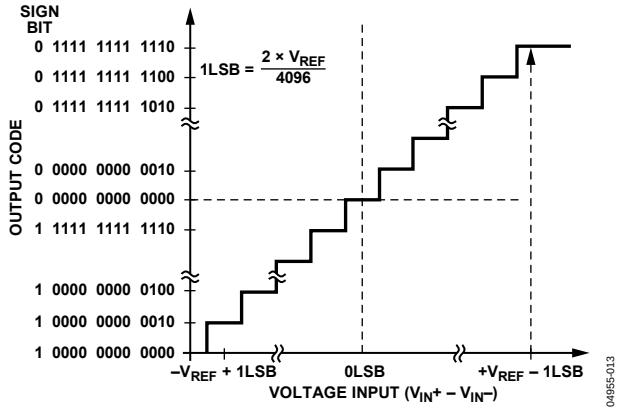


Figure 50. ADC Transfer Function in Differential Mode

NONVOLATILE FLASH/EE MEMORY

The ADuC7019/20/21/22/24/25/26/27/28/29 incorporate Flash/EE memory technology on-chip to provide the user with nonvolatile, in-circuit reprogrammable memory space.

Like EEPROM, flash memory can be programmed in-system at a byte level, although it must first be erased. The erase is performed in page blocks. As a result, flash memory is often and more correctly referred to as Flash/EE memory.

Overall, Flash/EE memory represents a step closer to the ideal memory device that includes nonvolatility, in-circuit programmability, high density, and low cost. Incorporated in the ADuC7019/20/21/22/24/25/26/27/28/29, Flash/EE memory technology allows the user to update program code space in-circuit, without the need to replace one-time programmable (OTP) devices at remote operating nodes.

Each part contains a 64 kB array of Flash/EE memory. The lower 62 kB is available to the user and the upper 2 kB contain permanently embedded firmware, allowing in-circuit serial download. These 2 kB of embedded firmware also contain a power-on configuration routine that downloads factory-calibrated coefficients to the various calibrated peripherals (such as ADC, temperature sensor, and band gap references). This 2 kB embedded firmware is hidden from user code.

Flash/EE Memory Reliability

The Flash/EE memory arrays on the parts are fully qualified for two key Flash/EE memory characteristics: Flash/EE memory cycling endurance and Flash/EE memory data retention.

Endurance quantifies the ability of the Flash/EE memory to be cycled through many program, read, and erase cycles. A single endurance cycle is composed of four independent, sequential events, defined as

1. Initial page erase sequence
2. Read/verify sequence (single Flash/EE)
3. Byte program sequence memory
4. Second read/verify sequence (endurance cycle)

In reliability qualification, every half word (16-bit wide) location of the three pages (top, middle, and bottom) in the Flash/EE memory is cycled 10,000 times from 0x0000 to 0xFFFF. As indicated in Table 1, the Flash/EE memory endurance qualification is carried out in accordance with JEDEC Retention Lifetime Specification A117 over the industrial temperature range of −40° to +125°C. The results allow the specification of a minimum endurance figure over a supply temperature of 10,000 cycles.

Retention quantifies the ability of the Flash/EE memory to retain its programmed data over time. Again, the parts are qualified in accordance with the formal JEDEC Retention Lifetime Specification (A117) at a specific junction temperature (T_J = 85°C). As part of this qualification procedure, the Flash/EE memory is cycled to its specified endurance limit, described in Table 1, before data retention is characterized. This means that the Flash/EE memory is guaranteed to retain its data for its fully specified retention lifetime every time the Flash/EE memory is reprogrammed. In addition, note that retention lifetime, based on an activation energy of 0.6 eV, derates with T_J as shown in Figure 61.

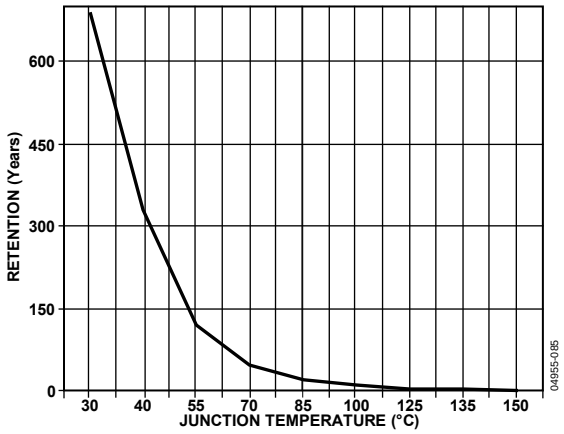


Figure 61. Flash/EE Memory Data Retention

PROGRAMMING

The 62 kB of Flash/EE memory can be programmed in-circuit, using the serial download mode or the provided JTAG mode.

Serial Downloading (In-Circuit Programming)

The ADuC7019/20/21/22/24/25/26/27/28/29 facilitate code download via the standard UART serial port or via the I²C port. The parts enter serial download mode after a reset or power cycle if the BM pin is pulled low through an external 1 kΩ resistor. After a part is in serial download mode, the user can download code to the full 62 kB of Flash/EE memory while the device is in-circuit in its target application hardware. An executable PC serial download is provided as part of the development system for serial downloading via the UART. The AN-806 Application Note describes the protocol for serial downloading via the I²C.

JTAG Access

The JTAG protocol uses the on-chip JTAG interface to facilitate code download and debug.

The PWMDAT1 register is a 10-bit register with a maximum value of 0x3FF (= 1023), which corresponds to a maximum programmed dead time of

$$t_{D(max)} = 1023 \times 2 \times t_{CORE} = 1023 \times 2 \times 24 \times 10^{-9} = 48.97\ \mu s$$

for a core clock of 41.78 MHz.

The dead time can be programmed to be zero by writing 0 to the PWMDAT1 register.

PWM Operating Mode (PWMCON and PWMSTA MMRs)

As discussed in the 3-Phase PWM section, the PWM controller of the ADuC7019/20/21/22/24/25/26/27/28/29 can operate in two distinct modes: single update mode and double update mode. The operating mode of the PWM controller is determined by the state of Bit 2 of the PWMCON register. If this bit is cleared, the PWM operates in the single update mode. Setting Bit 2 places the PWM in the double update mode. The default operating mode is single update mode.

In single update mode, a single PWMSYNC pulse is produced in each PWM period. The rising edge of this signal marks the start of a new PWM cycle and is used to latch new values from the PWM configuration registers (PWMDAT0 and PWMDAT1) and the PWM duty cycle registers (PWMCH0, PWMCH1, and PWMCH2) into the 3-phase timing unit. In addition, the PWMEN register is latched into the output control unit on the rising edge of the PWMSYNC pulse. In effect, this means that the characteristics and resulting duty cycles of the PWM signals can be updated only once per PWM period at the start of each cycle. The result is symmetrical PWM patterns about the midpoint of the switching period.

In double update mode, there is an additional PWMSYNC pulse produced at the midpoint of each PWM period. The rising edge of this new PWMSYNC pulse is again used to latch new values of the PWM configuration registers, duty cycle registers, and the PWMEN register. As a result, it is possible to alter both the characteristics (switching frequency and dead time) as well as the output duty cycles at the midpoint of each PWM cycle. Consequently, it is also possible to produce PWM switching patterns that are no longer symmetrical about the midpoint of the period (asymmetrical PWM patterns). In double update mode, it could be necessary to know whether operation at any point in time is in either the first half or the second half of the PWM cycle. This information is provided by Bit 0 of the PWMSTA register, which is cleared during operation in the first half of each PWM period (between the rising edge of the original PWMSYNC pulse and the rising edge of the new PWMSYNC pulse introduced in double update mode). Bit 0 of the PWMSTA register is set during operation in the second half of each PWM period. This status bit allows the user to make a determination of the particular half cycle during implementation of the PWMSYNC interrupt service routine, if required.

The advantage of double update mode is that lower harmonic voltages can be produced by the PWM process, and faster control bandwidths are possible. However, for a given PWM switching frequency, the PWMSYNC pulses occur at twice the rate in the double update mode. Because new duty cycle values must be computed in each PWMSYNC interrupt service routine, there is a larger computational burden on the ARM core in double update mode.

PWM Duty Cycles (PWMCH0, PWMCH1, and PWMCH2 MMRs)

The duty cycles of the six PWM output signals on Pin $PWM0_H$ to Pin $PWM2_L$ are controlled by the three 16-bit read/write duty cycle registers, PWMCH0, PWMCH1, and PWMCH2. The duty cycle registers are programmed in integer counts of the fundamental time unit, t_{CORE}. They define the desired on time of the high-side PWM signal produced by the 3-phase timing unit over half the PWM period. The switching signals produced by the 3-phase timing unit are also adjusted to incorporate the programmed dead time value in the PWMDAT1 register. The 3-phase timing unit produces active high signals so that a high level corresponds to a command to turn on the associated power device.

Figure 69 shows a typical pair of PWM outputs (in this case, 0H and 0L) from the timing unit in single update mode. All illustrated time values indicate the integer value in the associated register and can be converted to time by simply multiplying by the fundamental time increment, t_{CORE}. Note that the switching patterns are perfectly symmetrical about the midpoint of the switching period in this mode because the same values of PWMCH0, PWMDAT0, and PWMDAT1 are used to define the signals in both half cycles of the period.

Figure 69 also demonstrates how the programmed duty cycles are adjusted to incorporate the desired dead time into the resulting pair of PWM signals. The dead time is incorporated by moving the switching instants of both PWM signals (0H and 0L) away from the instant set by the PWMCH0 register.

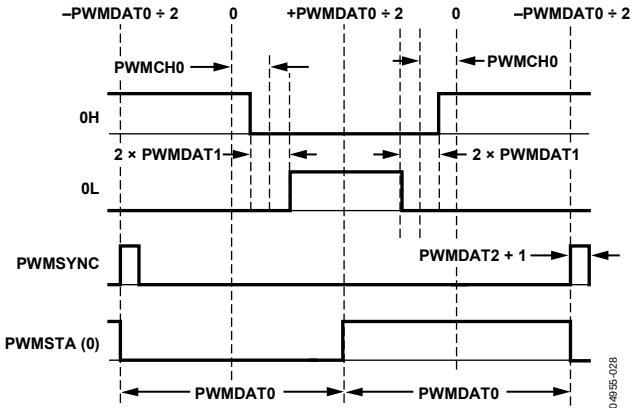


Figure 69. Typical PWM Outputs of the 3-Phase Timing Unit (Single Update Mode)

Both switching edges are moved by an equal amount (PWMDAT1 × t_{CORE}) to preserve the symmetrical output patterns.

Also shown are the PWMSYNC pulse and Bit 0 of the PWMSTA register, which indicates whether operation is in the first or second half cycle of the PWM period.

The resulting on times of the PWM signals over the full PWM period (two half periods) produced by the timing unit can be written as follows:

On the high side

$$t_{0HH} = PWMDAT0 + 2(PWMCH0 - PWMDAT1) \times t_{CORE}$$

$$t_{0HL} = PWMDAT0 - 2(PWMCH0 - PWMDAT1) \times t_{CORE}$$

and the corresponding duty cycles (*d*)

$$d_{0H} = t_{0HH}/t_S = ½ + (PWMCH0 - PWMDAT1)/PWMDAT0$$

and on the low side

$$t_{0LH} = PWMDAT0 - 2(PWMCH0 + PWMDAT1) \times t_{CORE}$$

$$t_{0LL} = PWMDAT0 + 2(PWMCH0 + PWMDAT1) \times t_{CORE}$$

and the corresponding duty cycles (*d*)

$$d_{OL} = t_{0LH}/t_S = ½ - (PWMCH0 + PWMDAT1)/PWMDAT0$$

The minimum permissible t_{0H} and t_{0L} values are zero, corresponding to a 0% duty cycle. In a similar fashion, the maximum value is t_S, corresponding to a 100% duty cycle.

Figure 70 shows the output signals from the timing unit for operation in double update mode. It illustrates a general case where the switching frequency, dead time, and duty cycle are all changed in the second half of the PWM period. The same value for any or all of these quantities can be used in both halves of the PWM cycle. However, there is no guarantee that symmetrical PWM signals are produced by the timing unit in double update mode. Figure 70 also shows that the dead time insertions into the PWM signals are done in the same way as in single update mode.

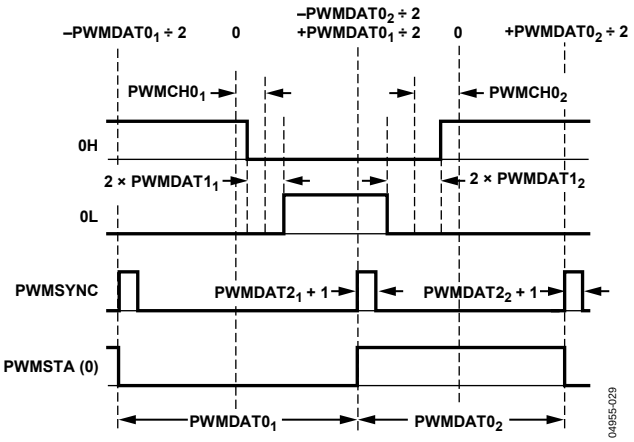


Figure 70. Typical PWM Outputs of the 3-Phase Timing Unit (Double Update Mode)

In general, the on times of the PWM signals in double update mode can be defined as follows:

On the high side

$$t_{0HH} = (PWMDAT0_1/2 + PWMDAT0_2/2 + PWMCH0_1 + PWMCH0_2 - PWMDAT1_1 - PWMDAT1_2) \times t_{CORE}$$

$$t_{0HL} = (PWMDAT0_1/2 + PWMDAT0_2/2 - PWMCH0_1 - PWMCH0_2 + PWMDAT1_1 + PWMDAT1_2) \times t_{CORE}$$

where Subscript *1* refers to the value of that register during the first half cycle, and Subscript *2* refers to the value during the second half cycle.

The corresponding duty cycles (*d*) are

$$d_{0H} = t_{0HH}/t_S = (PWMDAT0_1/2 + PWMDAT0_2/2 + PWMCH0_1 + PWMCH0_2 - PWMDAT1_1 - PWMDAT1_2)/(PWMDAT0_1 + PWMDAT0_2)$$

On the low side

$$t_{0LH} = (PWMDAT0_1/2 + PWMDAT0_2/2 + PWMCH0_1 + PWMCH0_2 + PWMDAT1_1 + PWMDAT1_2) \times t_{CORE}$$

$$t_{0LL} = (PWMDAT0_1/2 + PWMDAT0_2/2 - PWMCH0_1 - PWMCH0_2 - PWMDAT1_1 - PWMDAT1_2) \times t_{CORE}$$

where Subscript *1* refers to the value of that register during the first half cycle, and Subscript *2* refers to the value during the second half cycle.

The corresponding duty cycles (d) are

$$d_{0L} = t_{0LH}/t_S = (\text{PWMDAT0}_1/2 + PWMDAT0_2/2 + PWMCH0_1 + PWMCH0_2 + PWMDAT1_1 + PWMDAT1_2)/(PWMDAT0_1 + PWMDAT0_2)$$

For the completely general case in double update mode (see Figure 70), the switching period is given by

$$t_S = (PWMDAT0_1 + PWMDAT0_2) \times t_{CORE}$$

Again, the values of t_{0H} and t_{0L} are constrained to lie between zero and t_S.

PWM signals similar to those illustrated in Figure 69 and Figure 70 can be produced on the 1H, 1L, 2H, and 2L outputs by programming the PWMCH1 and PWMCH2 registers in a manner identical to that described for PWMCH0. The PWM controller does not produce any PWM outputs until all of the PWMDAT0, PWMCH0, PWMCH1, and PWMCH2 registers have been written to at least once. When these registers are written, internal counting of the timers in the 3-phase timing unit is enabled.

Writing to the PWMDAT0 register starts the internal timing of the main PWM timer. Provided that the PWMDAT0 register is written to prior to the PWMCH0, PWMCH1, and PWMCH2 registers in the initialization, the first PWMSYNC pulse and interrupt (if enabled) appear 1.5 × t_{CORE} × PWMDAT0 seconds after the initial write to the PWMDAT0 register in single update mode. In double update mode, the first PWMSYNC pulse appears after PWMDAT0 × t_{CORE} seconds.

Table 85. GPxDAT Registers

Name	Address	Default Value[1]	Access
GP0DAT	0xFFFFF420	0x000000XX	R/W
GP1DAT	0xFFFFF430	0x000000XX	R/W
GP2DAT	0xFFFFF440	0x000000XX	R/W
GP3DAT	0xFFFFF450	0x000000XX	R/W
GP4DAT	0xFFFFF460	0x000000XX	R/W

[1] X = 0, 1, 2, or 3.

GPxDAT are Port x configuration and data registers. They configure the direction of the GPIO pins of Port x, set the output value for the pins configured as output, and store the input value of the pins configured as input.

Table 86. GPxDAT MMR Bit Descriptions

Bit	Description
31:24	Direction of the data. Set to 1 by user to configure the GPIO pin as an output. Cleared to 0 by user to configure the GPIO pin as an input.
23:16	Port x data output.
15:8	Reflect the state of Port x pins at reset (read only).
7:0	Port x data input (read only).

Table 87. GPxSET Registers

Name	Address	Default Value[1]	Access
GP0SET	0xFFFFF424	0x000000XX	W
GP1SET	0xFFFFF434	0x000000XX	W
GP2SET	0xFFFFF444	0x000000XX	W
GP3SET	0xFFFFF454	0x000000XX	W
GP4SET	0xFFFFF464	0x000000XX	W

[1] X = 0, 1, 2, or 3.

GPxSET are data set Port x registers.

Table 88. GPxSET MMR Bit Descriptions

Bit	Description
31:24	Reserved.
23:16	Data Port x set bit. Set to 1 by user to set bit on Port x; also sets the corresponding bit in the GPxDAT MMR. Cleared to 0 by user; does not affect the data out.
15:0	Reserved.

Table 89. GPxCLR Registers

Name	Address	Default Value[1]	Access
GP0CLR	0xFFFFF428	0x000000XX	W
GP1CLR	0xFFFFF438	0x000000XX	W
GP2CLR	0xFFFFF448	0x000000XX	W
GP3CLR	0xFFFFF458	0x000000XX	W
GP4CLR	0xFFFFF468	0x000000XX	W

[1] X = 0, 1, 2, or 3.

GPxCLR are data clear Port x registers.

Table 90. GPxCLR MMR Bit Descriptions

Bit	Description
31:24	Reserved.
23:16	Data Port x clear bit. Set to 1 by user to clear bit on Port x; also clears the corresponding bit in the GPxDAT MMR. Cleared to 0 by user; does not affect the data out.
15:0	Reserved.

SERIAL PORT MUX

The serial port mux multiplexes the serial port peripherals (an SPI, UART, and two I^2Cs) and the programmable logic array (PLA) to a set of 10 GPIO pins. Each pin must be configured to one of its specific I/O functions as described in Table 91.

Table 91. SPM Configuration

SPMMUX	GPIO (00)	UART (01)	UART/I^2C/SPI (10)	PLA (11)
SPM0	P1.0	SIN	I2C0SCL	PLAI[0]
SPM1	P1.1	SOUT	I2C0SDA	PLAI[1]
SPM2	P1.2	RTS	I2C1SCL	PLAI[2]
SPM3	P1.3	CTS	I2C1SDA	PLAI[3]
SPM4	P1.4	RI	SCLK	PLAI[4]
SPM5	P1.5	DCD	MISO	PLAI[5]
SPM6	P1.6	DSR	MOSI	PLAI[6]
SPM7	P1.7	DTR	$\overline{CS}$	PLAO[0]
SPM8	P0.7	ECLK/XCLK	SIN	PLAO[4]
SPM9	P2.0	CONV	SOUT	PLAO[5]

Table 91 also details the mode for each of the SPMMUX pins. This configuration must be done via the GP0CON, GP1CON, and GP2CON MMRs. By default, these 10 pins are configured as GPIOs.

UART SERIAL INTERFACE

The UART peripheral is a full-duplex, universal, asynchronous receiver/transmitter. It is fully compatible with the 16,450 serial port standard. The UART performs serial-to-parallel conversions on data characters received from a peripheral device or modem, and parallel-to-serial conversions on data characters received from the CPU. The UART includes a fractional divider for baud rate generation and has a network addressable mode. The UART function is made available on the 10 pins of the ADuC7019/20/21/22/24/25/26/27/28/29 (see Table 92).

Table 92. UART Signal Description

Pin	Signal	Description
SPM0 (Mode 1)	SIN	Serial receive data.
SPM1 (Mode 1)	SOUT	Serial transmit data.
SPM2 (Mode 1)	RTS	Request to send.
SPM3 (Mode 1)	CTS	Clear to send.
SPM4 (Mode 1)	RI	Ring indicator.
SPM5 (Mode 1)	DCD	Data carrier detect.
SPM6 (Mode 1)	DSR	Data set ready.
SPM7 (Mode 1)	DTR	Data terminal ready.
SPM8 (Mode 2)	SIN	Serial receive data.
SPM9 (Mode 2)	SOUT	Serial transmit data.

Table 116. COMIID1 MMR Bit Descriptions

Bit 3:1 Status Bits	Bit 0 NINT	Priority	Definition	Clearing Operation
000	1		No interrupt	
110	0	2	Matching network address	Read COMRX
101	0	3	Address transmitted, buffer empty	Write data to COMTX or read COMIID0
011	0	1	Receive line status interrupt	Read COMSTA0
010	0	2	Receive buffer full interrupt	Read COMRX
001	0	3	Transmit buffer empty interrupt	Write data to COMTX or read COMIID0
000	0	4	Modem status interrupt	Read COMSTA1

Note that to receive a network address interrupt, the slave must ensure that Bit 0 of COMIEN0 (enable receive buffer full interrupt) is set to 1.

Table 117. COMADR Register

Name	Address	Default Value	Access
COMADR	0xFFFF0728	0xAA	R/W

COMADR is an 8-bit, read/write network address register that holds the address checked for by the network addressable UART. Upon receiving this address, the device interrupts the processor and/or sets the appropriate status bit in COMIID1.

SERIAL PERIPHERAL INTERFACE

The ADuC7019/20/21/22/24/25/26/27/28/29 integrate a complete hardware serial peripheral interface (SPI) on-chip. SPI is an industry standard, synchronous serial interface that allows eight bits of data to be synchronously transmitted and simultaneously received, that is, full duplex up to a maximum bit rate of 3.48 Mb, as shown in Table 118. The SPI interface is not operational with core clock divider (CD) bits. POWCON[2:0] = 6 or 7 in master mode.

The SPI port can be configured for master or slave operation. and typically consists of four pins: MISO (P1.5), MOSI (P1.6), SCLK (P1.4), and $\overline{CS}$ (P1.7).

On the transmit side, the SPITX register (and a TX shift register outside it) loads data onto the transmit pin (in slave mode, MISO; in master mode, MOSI). The transmit status bit, Bit 0, in SPISTA indicates whether there is valid data in the SPITX register.

Similarly, the receive data path consists of the SPIRX register (and an RX shift register). SPISTA, Bit 3 indicates whether there is valid data in the SPIRX register. If valid data in the SPIRX register is overwritten or if valid data in the RX shift register is discarded, SPISTA, Bit 5 (the overflow bit) is set.

MISO (Master In, Slave Out) Pin

The MISO pin is configured as an input line in master mode and an output line in slave mode. The MISO line on the master (data in) should be connected to the MISO line in the slave device (data out). The data is transferred as byte wide (8-bit) serial data, MSB first.

MOSI (Master Out, Slave In) Pin

The MOSI pin is configured as an output line in master mode and an input line in slave mode. The MOSI line on the master (data out) should be connected to the MOSI line in the slave device (data in). The data is transferred as byte wide (8-bit) serial data, MSB first.

SCLK (Serial Clock I/O) Pin

The master serial clock (SCLK) is used to synchronize the data being transmitted and received through the MOSI SCLK period. Therefore, a byte is transmitted/received after eight SCLK periods. The SCLK pin is configured as an output in master mode and as an input in slave mode.

In master mode, the polarity and phase of the clock are controlled by the SPICON register, and the bit rate is defined in the SPIDIV register as follows:

$$f_{SERIAL\,CLOCK} = \frac{f_{UCLK}}{2\times(1+SPIDIV)}$$

The maximum speed of the SPI clock is dependent on the clock divider bits and is summarized in Table 118.

Table 118. SPI Speed vs. Clock Divider Bits in Master Mode

CD Bits	0	1	2	3	4	5
SPIDIV in Hex	0x05	0x0B	0x17	0x2F	0x5F	0xBF
SPI dpeed in MHz	3.482	1.741	0.870	0.435	0.218	0.109

In slave mode, the SPICON register must be configured with the phase and polarity of the expected input clock. The slave accepts data from an external master up to 10.4 Mb at CD = 0. The formula to determine the maximum speed is as follows:

$$f_{SERIAL\,CLOCK} = \frac{f_{HCLK}}{4}$$

In both master and slave modes, data is transmitted on one edge of the SCL signal and sampled on the other. Therefore, it is important that the polarity and phase be configured the same for the master and slave devices.

Chip Select ($\overline{CS}$ Input) Pin

In SPI slave mode, a transfer is initiated by the assertion of $\overline{CS}$, which is an active low input signal. The SPI port then transmits and receives 8-bit data until the transfer is concluded by deassertion of $\overline{CS}$. In slave mode, $\overline{CS}$ is always an input.

Table 180. T1CON MMR Bit Descriptions

Bit	Value	Description
31:18		Reserved.
17		Event select bit. Set by user to enable time capture of an event. Cleared by user to disable time capture of an event.
16:12		Event select range, 0 to 31. These events are as described in Table 160. All events are offset by two; that is, Event 2 in Table 160 becomes Event 0 for the purposes of Timer1.
11:9		Clock select.
	000	Core clock (HCLK).
	001	External 32.768 kHz crystal.
	010	P1.0 rising edge triggered.
	011	P0.6 rising edge triggered.
8		Count up. Set by user for Timer1 to count up. Cleared by user for Timer1 to count down by default.
7		Timer1 enable bit. Set by user to enable Timer1. Cleared by user to disable Timer1 by default.
6		Timer1 mode. Set by user to operate in periodic mode. Cleared by user to operate in free-running mode. Default mode.
5:4		Format.
	00	Binary.
	01	Reserved.
	10	Hr: min: sec: hundredths (23 hours to 0 hour).
	11	Hr: min: sec: hundredths (255 hours to 0 hour).
3:0		Prescale.
	0000	Source Clock/1.
	0100	Source Clock/16.
	1000	Source Clock/256.
	1111	Source Clock/32,768.

Table 181. T1CLRI Register

Name	Address	Default Value	Access
T1CLRI	0xFFFF032C	0xFF	W

T1CLRI is an 8-bit register. Writing any value to this register clears the Timer1 interrupt.

Table 182. T1CAP Register

Name	Address	Default Value	Access
T1CAP	0xFFFF0330	0x00000000	R/W

T1CAP is a 32-bit register. It holds the value contained in T1VAL when a particular event occurs. This event must be selected in T1CON.

Timer2 (Wake-Up Timer)

Timer2 is a 32-bit wake-up timer (count down or count up) with a programmable prescaler. The source can be the 32 kHz external crystal, the core clock frequency, or the internal 32 kHz oscillator. The clock source can be scaled by a factor of 1, 16, 256, or 32,768. The wake-up timer continues to run when the core clock is disabled.

The counter can be formatted as plain 32-bit value or as hours: minutes: seconds: hundredths.

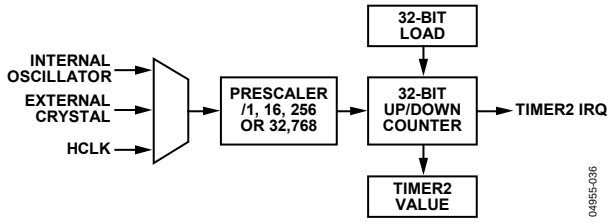


Figure 79. Timer2 Block Diagram

The Timer2 interface consists of four MMRs: T2LD, T2VAL, T2CON, and T2CLRI.

Table 183. T2LD Register

Name	Address	Default Value	Access
T2LD	0xFFFF0340	0x00000000	R/W

T2LD is a 32-bit register load register.

Table 184. T2VAL Register

Name	Address	Default Value	Access
T2VAL	0xFFFF0344	0xFFFFFFFF	R

T2VAL is a 32-bit read-only register that represents the current state of the counter.

Table 185. T2CON Register

Name	Address	Default Value	Access
T2CON	0xFFFF0348	0x0000	R/W

T2CON is the configuration MMR described in Table 186.

Table 191. T3CON MMR Bit Descriptions

Bit	Value	Description
15:9		Reserved.
8		Count up. Set by user for Timer3 to count up. Cleared by user for Timer3 to count down by default.
7		Timer3 enable bit. Set by user to enable Timer3. Cleared by user to disable Timer3 by default.
6		Timer3 mode. Set by user to operate in periodic mode. Cleared by user to operate in free-running mode. Default mode.
5		Watchdog mode enable bit. Set by user to enable watchdog mode. Cleared by user to disable watchdog mode by default.
4		Secure clear bit. Set by user to use the secure clear option. Cleared by user to disable the secure clear option by default.
3:2		Prescale.
	00	Source Clock/1 by default.
	01	Source Clock/16.
	10	Source Clock/256.
	11	Undefined. Equivalent to 00.
1		Watchdog IRQ option bit. Set by user to produce an IRQ instead of a reset when the watchdog reaches 0. Cleared by user to disable the IRQ option.
0		Reserved.

Table 192. T3CLRI Register

Name	Address	Default Value	Access
T3CLRI	0xFFFF036C	0x00	W

T3CLRI is an 8-bit register. Writing any value to this register on successive occassions clears the Timer3 interrupt in normal mode or resets a new timeout period in watchdog mode.

Note that the user must perform successive writes to this register to ensure resetting the timeout period.

Secure Clear Bit (Watchdog Mode Only)

The secure clear bit is provided for a higher level of protection. When set, a specific sequential value must be written to T3CLRI to avoid a watchdog reset. The value is a sequence generated by the 8-bit linear feedback shift register (LFSR) polynomial = X8 + X6 + X5 + X + 1, as shown in Figure 81.

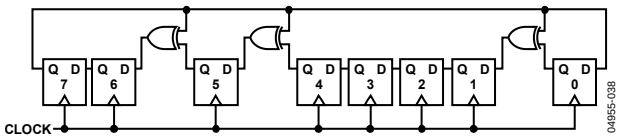


Figure 81. 8-Bit LFSR

The initial value or seed is written to T3CLRI before entering watchdog mode. After entering watchdog mode, a write to T3CLRI must match this expected value. If it matches, the LFSR is advanced to the next state when the counter reload occurs. If it fails to match the expected state, a reset is immediately generated, even if the count has not yet expired.

The value 0x00 should not be used as an initial seed due to the properties of the polynomial. The value 0x00 is always guaranteed to force an immediate reset. The value of the LFSR cannot be read; it must be tracked/generated in software.

The following is an example of a sequence:

1. Enter initial seed, 0xAA, in T3CLRI before starting Timer3 in watchdog mode.
2. Enter 0xAA in T3CLRI; Timer3 is reloaded.
3. Enter 0x37 in T3CLRI; Timer3 is reloaded.
4. Enter 0x6E in T3CLRI; Timer3 is reloaded.
5. Enter 0x66. 0xDC was expected; the watchdog resets the chip.

EXTERNAL MEMORY INTERFACING

The ADuC7026 and ADuC7027 are the only models in their series that feature an external memory interface. The external memory interface requires a larger number of pins. This is why it is only available on larger pin count packages. The XMCFG MMR must be set to 1 to use the external port.

Although 32-bit addresses are supported internally, only the lower 16 bits of the address are on external pins.

The memory interface can address up to four 128 kB blocks of asynchronous memory (SRAM or/and EEPROM).

The pins required for interfacing to an external memory are shown in Table 193.

Table 193. External Memory Interfacing Pins

Pin	Function
AD[16:1]	Address/data bus
A16	Extended addressing for 8-bit memory only
MS[3:0]	Memory select
$\overline{WS}$	Write strobe
$\overline{RS}$	Read strobe
AE	Address latch enable
$\overline{BHE}$, $\overline{BLE}$	Byte write capability

There are four external memory regions available, as described in Table 194. Associated with each region are the MS[3:0] pins. These signals allow access to the particular region of external memory. The size of each memory region can be 128 kB maximum, 64 k × 16 or 128 k × 8. To access 128 k with an 8-bit memory, an extra address line (A16) is provided (see the example in Figure 82). The four regions are configured independently.

Table 194. Memory Regions

Address Start	Address End	Contents
0x10000000	0x1000FFFF	External Memory 0
0x20000000	0x2000FFFF	External Memory 1
0x30000000	0x3000FFFF	External Memory 2
0x40000000	0x4000FFFF	External Memory 3

Each external memory region can be controlled through three MMRs: XMCFG, XMxCON, and XMxPAR.

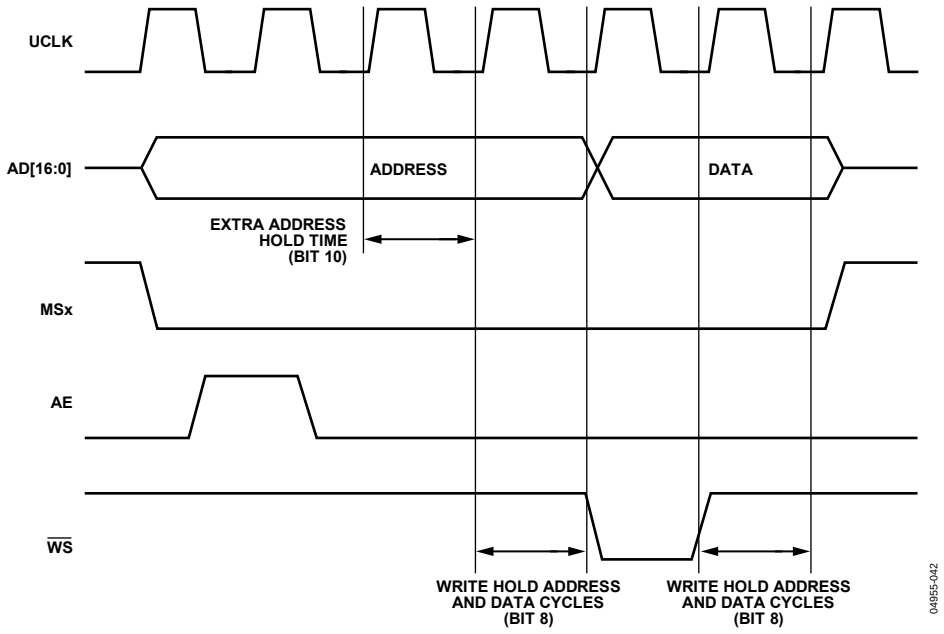


Figure 85. External Memory Write Cycle with Address and Write Hold Cycles

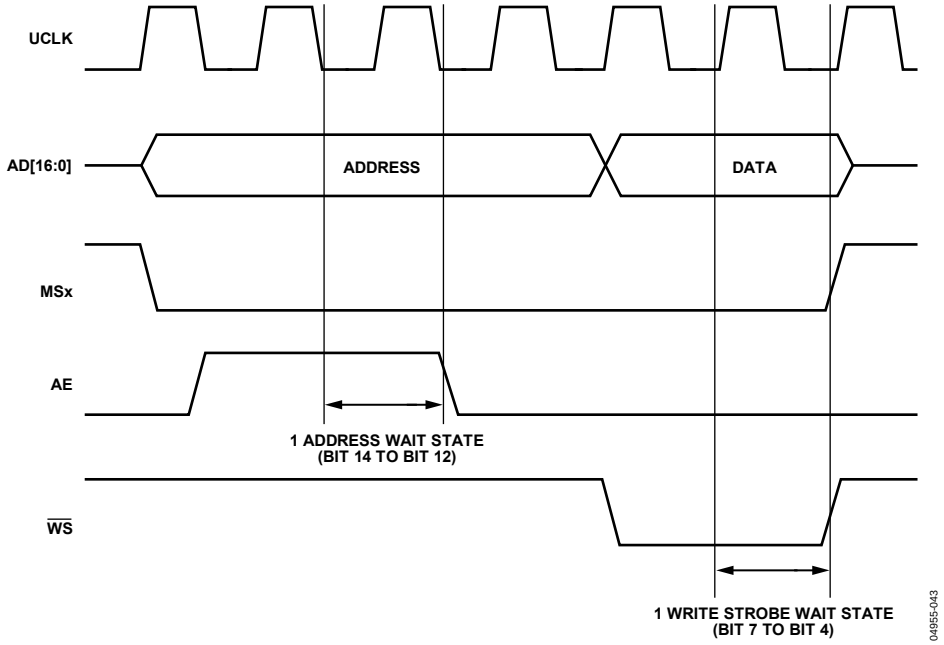


Figure 86. External Memory Write Cycle with Wait States

HARDWARE DESIGN CONSIDERATIONS

POWER SUPPLIES

The ADuC7019/20/21/22/24/25/26/27/28/29 operational power supply voltage range is 2.7 V to 3.6 V. Separate analog and digital power supply pins (AV_{DD} and IOV_{DD}, respectively) allow AV_{DD} to be kept relatively free of noisy digital signals often present on the system IOV_{DD} line. In this mode, the part can also operate with split supplies; that is, it can use different voltage levels for each supply. For example, the system can be designed to operate with an IOV_{DD} voltage level of 3.3 V whereas the AV_{DD} level can be at 3 V or vice versa. A typical split supply configuration is shown in Figure 87.

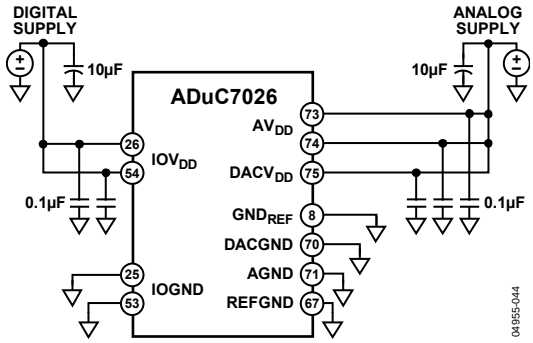


Figure 87. External Dual Supply Connections

As an alternative to providing two separate power supplies, the user can reduce noise on AV_{DD} by placing a small series resistor and/or ferrite bead between AV_{DD} and IOV_{DD} and then decoupling AV_{DD} separately to ground. An example of this configuration is shown in Figure 88. With this configuration, other analog circuitry (such as op amps and voltage reference) can be powered from the AV_{DD} supply line as well.

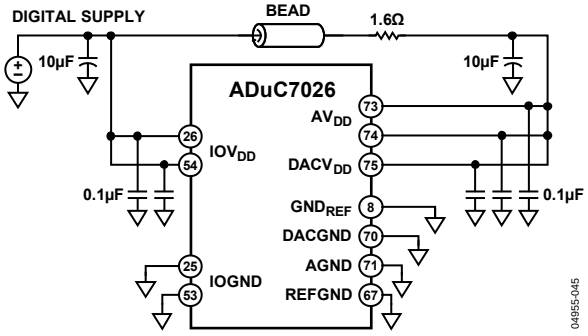


Figure 88. External Single Supply Connections

Note that in both Figure 87 and Figure 88, a large value (10 µF) reservoir capacitor sits on IOV_{DD}, and a separate 10 µF capacitor sits on AV_{DD}. In addition, local small-value (0.1 µF) capacitors are located at each AV_{DD} and IOV_{DD} pin of the chip. As per standard design practice, be sure to include all of these capacitors and ensure that the smaller capacitors are close to each AV_{DD} pin with trace lengths as short as possible. Connect the ground terminal of each of these capacitors directly to the underlying ground plane.

Finally, note that the analog and digital ground pins on the ADuC7019/20/21/22/24/25/26/27/28/29 must be referenced to the same system ground reference point at all times.

IOV_{DD} Supply Sensitivity

The IOV_{DD} supply is sensitive to high frequency noise because it is the supply source for the internal oscillator and PLL circuits. When the internal PLL loses lock, the clock source is removed by a gating circuit from the CPU, and the ARM7TDMI core stops executing code until the PLL regains lock. This feature ensures that no flash interface timings or ARM7TDMI timings are violated.

Typically, frequency noise greater than 50 kHz and 50 mV p-p on top of the supply causes the core to stop working.

If decoupling values recommended in the Power Supplies section do not sufficiently dampen all noise sources below 50 mV on IOV_{DD}, a filter such as the one shown in Figure 89 is recommended.

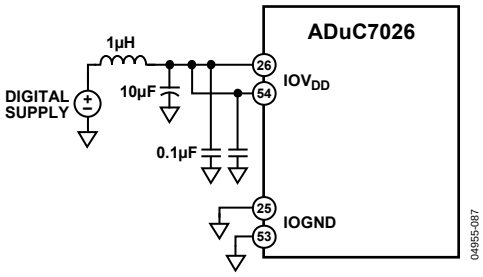


Figure 89. Recommended IOV_{DD} Supply Filter

Linear Voltage Regulator

Each ADuC7019/20/21/22/24/25/26/27/28/29 requires a single 3.3 V supply, but the core logic requires a 2.6 V supply. An on-chip linear regulator generates the 2.6 V from IOV_{DD} for the core logic. The LV_{DD} pin is the 2.6 V supply for the core logic. An external compensation capacitor of 0.47 µF must be connected between LV_{DD} and DGND (as close as possible to these pins) to act as a tank of charge as shown in Figure 90.

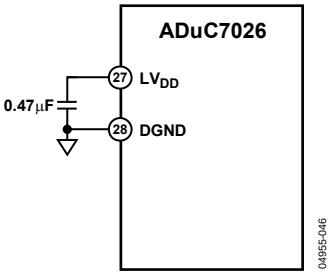
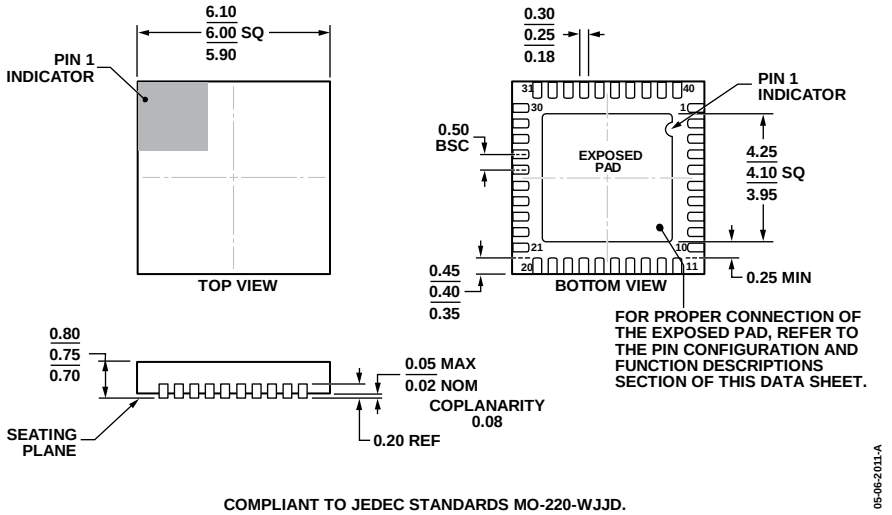


Figure 90. Voltage Regulator Connections

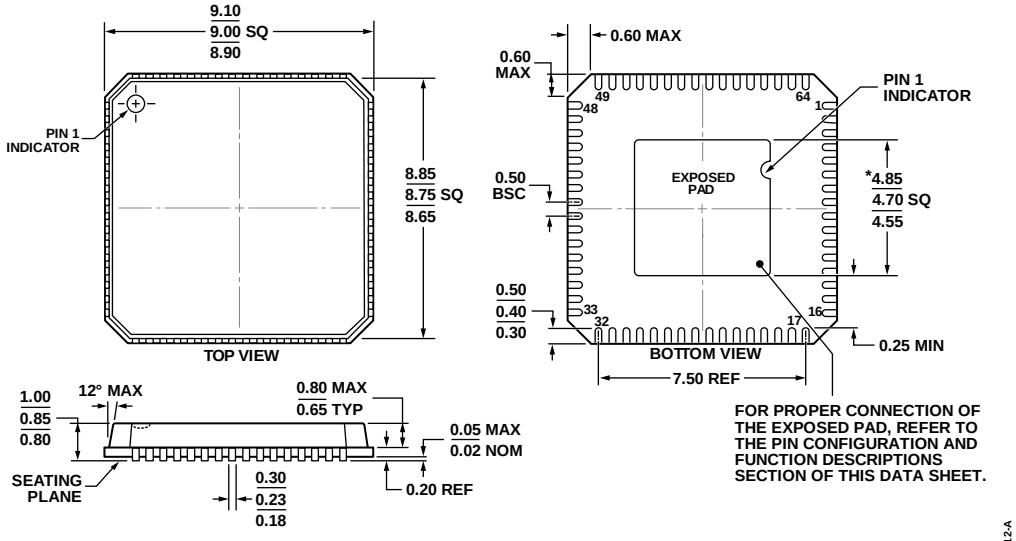
The LV_{DD} pin should not be used for any other chip. It is also recommended to use excellent power supply decoupling on IOV_{DD} to help improve line regulation performance of the on-chip voltage regulator.

OUTLINE DIMENSIONS



COMPLIANT TO JEDEC STANDARDS MO-220-WJJD.

Figure 96. 40-Lead Lead Frame Chip Scale Package [LFCSP_WQ]
6 × 6 mm Body, Very Very Thin Quad
(CP-40-9)
Dimensions shown in millimeters



*COMPLIANT TO JEDEC STANDARDS MO-220-VMMD-4
EXCEPT FOR EXPOSED PAD DIMENSION

Figure 97. 64-Lead Lead Frame Chip Scale Package [LFCSP_VQ]
9 mm × 9 mm Body, Very Thin Quad
(CP-64-1)
Dimensions shown in millimeters